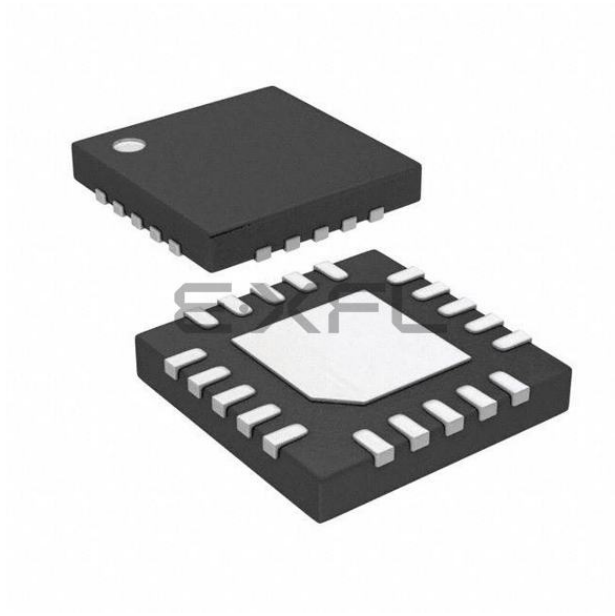

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-UFQFN Exposed Pad
Supplier Device Package	20-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1507-i-gz

Peripheral Features (Continued):

- Two Configurable Logic Cell (CLC) modules:
  - 16 selectable input source signals
  - Four inputs per module
  - Software control of combinational/sequential logic/state/clock functions
- Numerically Controlled Oscillator (NCO):
  - 20-bit accumulator
  - 16-bit increment
  - True linear frequency control
  - High-speed clock input
  - Selectable Output modes
    - Fixed Duty Cycle (FDC) mode
    - Pulse Frequency (PF) mode
- Complementary Waveform Generator (CWG):
  - Eight selectable signal sources
  - Selectable falling and rising edge dead-band control
  - Polarity control
  - Four auto-shutdown sources
  - Multiple input sources: PWM, CLC, NCO

PIC12(L)F1501/PIC16(L)F150X FAMILY TYPES

Device	Data Sheet Index	Program Memory Flash (words)	Data SRAM (bytes)	I/O's(2)	10-bit ADC (ch)	Comparators	DAC	Timers (8/16-bit)	PWM	EUSART	MSSP (I^2C/SPI)	CWG	CLC	NCO	Debug(1)	XLP
PIC12(L)F1501	(1)	1024	64	6	4	1	1	2/1	4	—	—	1	2	1	H	—
PIC16(L)F1503	(2)	2048	128	12	8	2	1	2/1	4	—	1	1	2	1	H	—
PIC16(L)F1507	(3)	2048	128	18	12	—	—	2/1	4	—	—	1	2	1	H	—
PIC16(L)F1508	(4)	4096	256	18	12	2	1	2/1	4	1	1	1	4	1	I/H	Y
PIC16(L)F1509	(4)	8192	512	18	12	2	1	2/1	4	1	1	1	4	1	I/H	Y

Note 1: Debugging Methods: (I) - Integrated on Chip; (H) - using Debug Header; (E) - using Emulation Header.
2: One pin is input-only.

Data Sheet Index: (Unshaded devices are described in this document.)

1: DS40001615 PIC12(L)F1501 Data Sheet, 8-Pin Flash, 8-bit Microcontrollers.
2: DS40001607 PIC16(L)F1503 Data Sheet, 14-Pin Flash, 8-bit Microcontrollers.
3: DS40001586 PIC16(L)F1507 Data Sheet, 20-Pin Flash, 8-bit Microcontrollers.
4: DS40001609 PIC16(L)F1508/9 Data Sheet, 20-Pin Flash, 8-bit Microcontrollers.

Note: For other small form-factor package availability and marking information, please visit **http://www.microchip.com/packaging** or contact your local sales office.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 31											
F8Ch — FE3h	—	Unimplemented								—	—
FE4h	STATUS_SHAD	—	—	—	—	—	Z_SHAD	DC_SHAD	C_SHAD	---- -xxx	---- -uuu
FE5h	WREG_SHAD	Working Register Shadow								xxxx xxxx	uuuu uuuu
FE6h	BSR_SHAD	—	—	—	Bank Select Register Shadow					---x xxxx	---u uuuu
FE7h	PCLATH_SHAD	—	Program Counter Latch High Register Shadow							-xxx xxxx	uuuu uuuu
FE8h	FSR0L_SHAD	Indirect Data Memory Address 0 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FE9h	FSR0H_SHAD	Indirect Data Memory Address 0 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FEAh	FSR1L_SHAD	Indirect Data Memory Address 1 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FEBh	FSR1H_SHAD	Indirect Data Memory Address 1 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FECh	—	Unimplemented								—	—
FEDh	STKPTR	—	—	—	Current Stack Pointer					---1 1111	---1 1111
FEEh	TOSL	Top-of-Stack Low byte								xxxx xxxx	uuuu uuuu
FEFh	TOSH	—	Top-of-Stack High byte							-xxx xxxx	-uuu uuuu

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved. Shaded locations are unimplemented, read as '0'.
Note 1: PIC16F1507 only.
2: Unimplemented, read as '1'.

4.6 Device ID and Revision ID

The memory location 8006h is where the Device ID and Revision ID are stored. The upper nine bits hold the Device ID. The lower five bits hold the Revision ID. See **Section 10.4 "User ID, Device ID and Configuration Word Access"** for more information on accessing these memory locations.

Development tools, such as device programmers and debuggers, may be used to read the Device ID and Revision ID.

4.7 Register Definitions: Device ID

REGISTER 4-3: DEVID: DEVICE ID REGISTER

R	R	R	R	R	R
DEV<8:3>					
bit 13					bit 8

R	R	R	R	R	R	R	R
DEV<2:0>			REV<4:0>				
bit 7							bit 0

Legend:	
R = Readable bit	
'1' = Bit is set	'0' = Bit is cleared

bit 13-5 **DEV<8:0>:** Device ID bits

Device	DEVID<13:0> Values	
	DEV<8:0>	REV<4:0>
PIC16LF1507	10 1101 110	x xxxx
PIC16F1507	10 1101 000	x xxxx

bit 4-0 **REV<4:0>:** Revision ID bits

These bits are used to identify the revision (see Table under DEV<8:0> above).

REGISTER 7-6: PIR2: PERIPHERAL INTERRUPT REQUEST REGISTER 2

U-0	U-0	U-0	U-0	U-0	R/W-0/0	U-0	U-0
—	—	—	—	—	NCO1IF	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

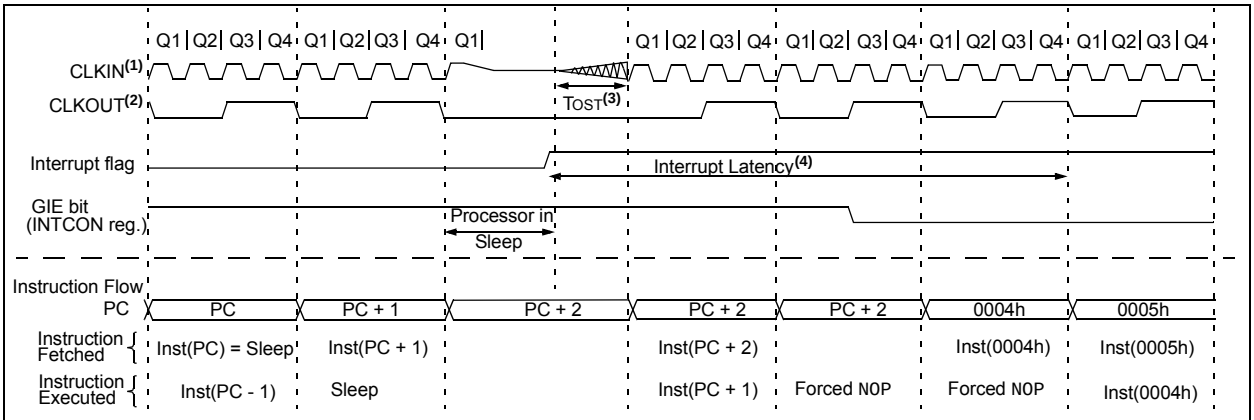
bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **NCO1IF:** Numerically Controlled Oscillator Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 1-0 **Unimplemented:** Read as ‘0’

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Interrupt Enable bit, GIE of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 8-1: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: External clock. High, Medium, Low mode assumed.
2: CLKOUT is shown here for timing reference.
3: TOST = 1024 TOSC. This delay does not apply to EC, RC and INTOSC Oscillator modes.
4: GIE = 1 assumed. In this case after wake-up, the processor calls the ISR at 0004h. If GIE = 0, execution will continue in-line.

8.2 Low-Power Sleep Mode

This device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode.

Low-Power Sleep mode allows the user to optimize the operating current in Sleep. Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register, putting the LDO and reference circuitry in a low-power state whenever the device is in Sleep.

8.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the Default Operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The Normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

8.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The LDO will remain in the Normal Power mode when those peripherals are enabled. The Low-Power Sleep mode is intended for use with these peripherals:

- Brown-out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source)

The Complementary Waveform Generator (CWG), the Numerically Controlled Oscillator (NCO) and the Configurable Logic Cell (CLC) modules can utilize the HFINTOSC oscillator as either a clock source or as an input source. Under certain conditions, when the HFINTOSC is selected for use with the CWG, NCO or CLC modules, the HFINTOSC will remain active during Sleep. This will have a direct effect on the Sleep mode current.

Please refer to sections **Section 20.5 “Operation During Sleep”**, **21.7 “Operation In Sleep”** and **22.10 “Operation During Sleep”** for more information.

Note:	The PIC16LF1507 does not have a configurable Low-Power Sleep mode. PIC16LF1507 is an unregulated device and is always in the lowest power state when in Sleep, with no wake-up time penalty. This device has a lower maximum VDD and I/O voltage than the PIC16F1507. See **Section 25.0 “Electrical Specifications”** for more information.

9.6 Register Definitions: Watchdog Timer Control

REGISTER 9-1: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	R/W-0/0	R/W-1/1	R/W-0/0	R/W-1/1	R/W-1/1	R/W-0/0
—	—	WDTPS<4:0>					SWDTEN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-1 **WDTPS<4:0>:** Watchdog Timer Period Select bits(1)

Bit Value = Prescale Rate

11111 = Reserved. Results in minimum interval (1:32)

•

•

•

10011 = Reserved. Results in minimum interval (1:32)

10010 = 1:8388608 (2^{23}) (Interval 256s nominal)
10001 = 1:4194304 (2^{22}) (Interval 128s nominal)
10000 = 1:2097152 (2^{21}) (Interval 64s nominal)
01111 = 1:1048576 (2^{20}) (Interval 32s nominal)
01110 = 1:524288 (2^{19}) (Interval 16s nominal)
01101 = 1:262144 (2^{18}) (Interval 8s nominal)
01100 = 1:131072 (2^{17}) (Interval 4s nominal)
01011 = 1:65536 (Interval 2s nominal) (Reset value)
01010 = 1:32768 (Interval 1s nominal)
01001 = 1:16384 (Interval 512 ms nominal)
01000 = 1:8192 (Interval 256 ms nominal)
00111 = 1:4096 (Interval 128 ms nominal)
00110 = 1:2048 (Interval 64 ms nominal)
00101 = 1:1024 (Interval 32 ms nominal)
00100 = 1:512 (Interval 16 ms nominal)
00011 = 1:256 (Interval 8 ms nominal)
00010 = 1:128 (Interval 4 ms nominal)
00001 = 1:64 (Interval 2 ms nominal)
00000 = 1:32 (Interval 1 ms nominal)

bit 0 **SWDTEN:** Software Enable/Disable for Watchdog Timer bit

If WDTE<1:0> = 1x:
This bit is ignored.
If WDTE<1:0> = 01:
1 = WDT is turned on
0 = WDT is turned off
If WDTE<1:0> = 00:
This bit is ignored.

Note 1: Times are approximate. WDT time is based on 31 kHz LFINTOSC.

REGISTER 10-6: PMCON2: PROGRAM MEMORY CONTROL 2 REGISTER

W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0
Program Memory Control Register 2							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **Flash Memory Unlock Pattern bits**

To unlock writes, a 55h must be written first, followed by an AAh, before setting the WR bit of the PMCON1 register. The value written to this register is used to unlock the writes. There are specific timing requirements on these writes.

TABLE 10-3: SUMMARY OF REGISTERS ASSOCIATED WITH FLASH PROGRAM MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	64
PMCON1	—(1)	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	93
PMCON2	Program Memory Control Register 2								94
PMADRL	PMADRL<7:0>								92
PMADRH	—(1)	PMADRH<6:0>							92
PMDATL	PMDATL<7:0>								92
PMDATH	—	—	PMDATH<5:0>						92

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Flash program memory.
Note 1: Unimplemented, read as '1'.

TABLE 10-4: SUMMARY OF CONFIGURATION WORD WITH RESETS

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	38
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		—	FOSC<1:0>		
CONFIG2	13:8	—	—	LVP	$\overline{\text{DEBUG}}$	$\overline{\text{LPBOR}}$	BORV	STVREN	—	39
	7:0	—	—	—	—	—	—	WRT<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Resets.

REGISTER 11-4: LATA: PORTA DATA LATCH REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	U-0	R/W-x/u	R/W-x/u	R/W-x/u
—	—	LATA5	LATA4	—	LATA2	LATA1	LATA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **LATA<5:4>**: RA<5:4> Output Latch Value bits(1)

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **LATA<2:0>**: RA<2:0> Output Latch Value bits(1)

Note 1: Writes to PORTA are actually written to corresponding LATA register. Reads from PORTA register is return of actual I/O pin values.

REGISTER 11-5: ANSELA: PORTA ANALOG SELECT REGISTER

U-0	U-0	U-0	R/W-1/1	U-0	R/W-1/1	R/W-1/1	R/W-1/1
—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **ANSA4**: Analog Select between Analog or Digital Function on pins RA4, respectively
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.
0 = Digital I/O. Pin is assigned to port or digital special function.

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **ANSA<2:0>**: Analog Select between Analog or Digital Function on pins RA<2:0>, respectively
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.
0 = Digital I/O. Pin is assigned to port or digital special function.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

14.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "*Use and Calibration of the Internal Temperature Indicator*" (DS01333) for more details regarding the calibration process.

14.1 Circuit Operation

Figure 14-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 14-1 describes the output characteristics of the temperature indicator.

EQUATION 14-1: V_{OUT} RANGES

High Range: $V_{OUT} = V_{DD} - 4V_T$

Low Range: $V_{OUT} = V_{DD} - 2V_T$

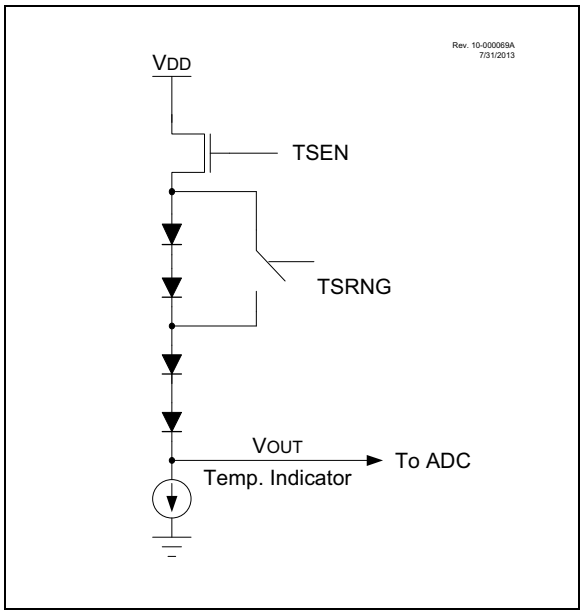
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 13.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register. When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher V_{DD} is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low voltage operation.

FIGURE 14-1: TEMPERATURE CIRCUIT DIAGRAM



14.2 Minimum Operating V_{DD}

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, V_{DD}, must be high enough to ensure that the temperature circuit is correctly biased.

Table 14-1 shows the recommended minimum V_{DD} vs. range setting.

TABLE 14-1: RECOMMENDED V_{DD} VS. RANGE

Min. V_{DD}, TSRNG = 1	Min. V_{DD}, TSRNG = 0
3.6V	1.8V

14.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 15.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

14.4 ADC Acquisition Time

To ensure accurate temperature measurements, the user must wait at least 200 μs after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed. In addition, the user must wait 200 μs between sequential conversions of the temperature indicator output.

15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 11.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are 14 channel selections available:

- AN<11:0> pins
- Temperature Indicator
- FVR_buffer1

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay (T_{ACQ}) is required before starting the next conversion. Refer to **Section 15.2.6 "ADC Conversion Procedure"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

The ADC module uses a positive and a negative voltage reference. The positive reference is labeled ref+ and the negative reference is labeled ref-.

The positive voltage reference (ref+) is selected by the ADPREF bits in the ADCON1 register. The positive voltage reference source can be:

- V_{REF}+ pin
- V_{DD}

The negative voltage reference (ref-) source is:

- V_{SS}

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- F_{OSC}/2
- F_{OSC}/4
- F_{OSC}/8
- F_{OSC}/16
- F_{OSC}/32
- F_{OSC}/64
- FRC (internal RC oscillator)

The time to complete one bit conversion is defined as T_{AD}. One full 10-bit conversion requires 11.5 T_{AD} periods as shown in Figure 15-2.

For correct conversion, the appropriate T_{AD} specification must be met. Refer to the ADC conversion requirements in **Section 25.0 "Electrical Specifications"** for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

15.1.5 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital conversion. The ADC Interrupt Flag is the ADIF bit in the PIR1 register. The ADC Interrupt Enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared in software.

Note 1:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.
2:	The ADC operates during Sleep only when the FRC oscillator is selected.

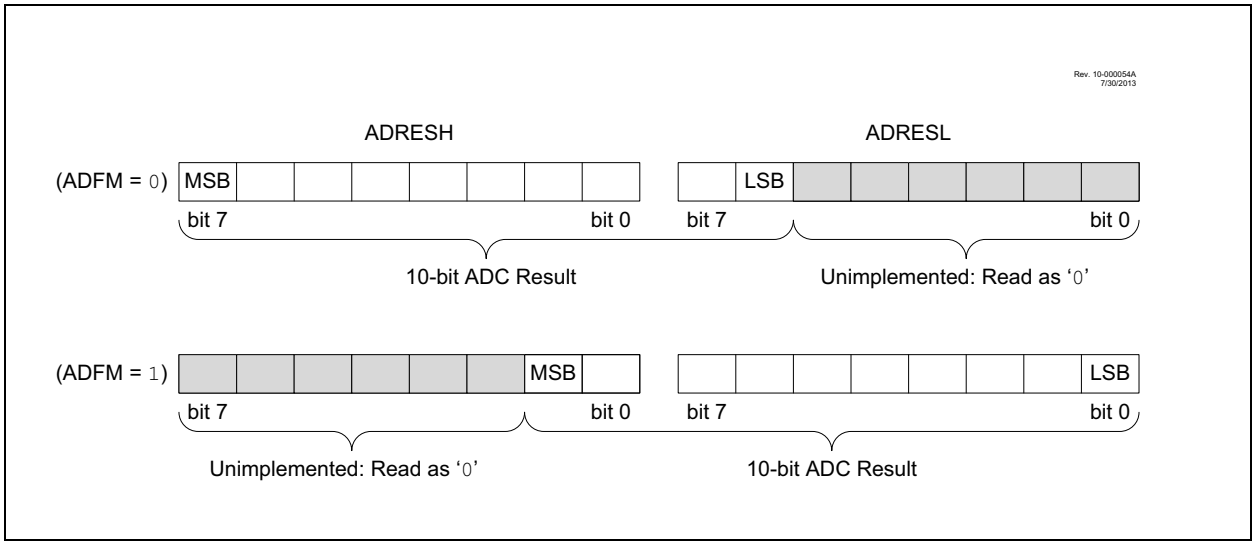
This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the GIE and PEIE bits of the INTCON register must be disabled. If the GIE and PEIE bits of the INTCON register are enabled, execution will switch to the Interrupt Service Routine.

15.1.6 RESULT FORMATTING

The 10-bit ADC conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON1 register controls the output format.

Figure 15-3 shows the two output formats.

FIGURE 15-3: 10-BIT ADC CONVERSION RESULT FORMAT



REGISTER 15-2: ADCON1: ADC CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
ADFM	ADCS<2:0>			—	—	ADPREF<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **ADFM:** ADC Result Format Select bit
1 = Right justified. Six Most Significant bits of ADRESH are set to ‘0’ when the conversion result is loaded.
0 = Left justified. Six Least Significant bits of ADRESL are set to ‘0’ when the conversion result is loaded.

bit 6-4 **ADCS<2:0>:** ADC Conversion Clock Select bits
000 = FOSC/2
001 = FOSC/8
010 = FOSC/32
011 = FRC (clock supplied from an internal RC oscillator)
100 = FOSC/4
101 = FOSC/16
110 = FOSC/64
111 = FRC (clock supplied from an internal RC oscillator)

bit 3-2 **Unimplemented**: Read as ‘0’

bit 1-0 **ADPREF<1:0>:** ADC Positive Voltage Reference Configuration bits
00 = VRPOS is connected to VDD
01 = Reserved
10 = VRPOS is connected to external VREF+ pin(1)
11 = Reserved

Note 1: When selecting the VREF+ pin as the source of the positive reference, be aware that a minimum voltage specification exists. See **Section 25.0 “Electrical Specifications”** for details.

REGISTER 20-4: CLCxSEL1: MULTIPLEXER DATA 3 AND 4 SELECT REGISTER

U-0	R/W-x/u	R/W-x/u	R/W-x/u	U-0	R/W-x/u	R/W-x/u	R/W-x/u
—	LCxD4S<2:0>(1)			—	LCxD3S<2:0>(1)		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **LCxD4S<2:0>:** Input Data 4 Selection Control bits(1)

- 111 = LCx_in[3] is selected for lcxd4
- 110 = LCx_in[2] is selected for lcxd4
- 101 = LCx_in[1] is selected for lcxd4
- 100 = LCx_in[0] is selected for lcxd4
- 011 = LCx_in[15] is selected for lcxd4
- 010 = LCx_in[14] is selected for lcxd4
- 001 = LCx_in[13] is selected for lcxd4
- 000 = LCx_in[12] is selected for lcxd4

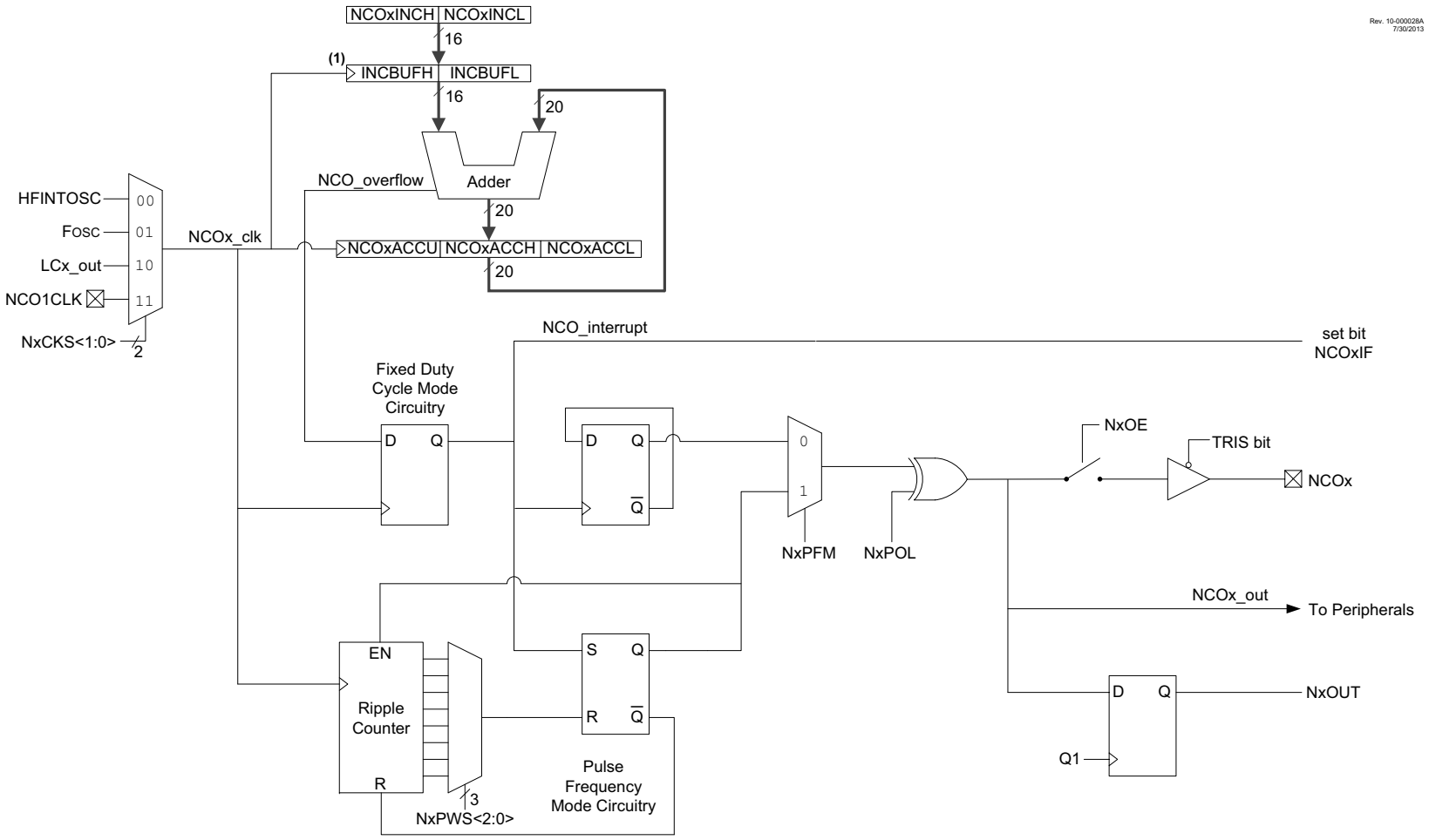
bit 3 **Unimplemented:** Read as '0'

bit 2-0 **LCxD3S<2:0>:** Input Data 3 Selection Control bits(1)

- 111 = LCx_in[15] is selected for lcxd3
- 110 = LCx_in[14] is selected for lcxd3
- 101 = LCx_in[13] is selected for lcxd3
- 100 = LCx_in[12] is selected for lcxd3
- 011 = LCx_in[11] is selected for lcxd3
- 010 = LCx_in[10] is selected for lcxd3
- 001 = LCx_in[9] is selected for lcxd3
- 000 = LCx_in[8] is selected for lcxd3

Note 1: See Table 20-1 for signal names associated with inputs.

FIGURE 21-1: NUMERICALLY CONTROLLED OSCILLATOR (NCOx) MODULE SIMPLIFIED BLOCK DIAGRAM



Note 1: The increment registers are double-buffered to allow for value changes to be made without first disabling the NCO module. The full increment value is loaded into the buffer registers on the second rising edge of the NCOx_clk signal that occurs immediately after a write to NCOxINCL register. The buffers are not user-accessible and are shown here for reference.

REGISTER 22-3: CWGxCON2: CWG CONTROL REGISTER 2

R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0
GxASE	GxARSEN	—	—	—	—	GxASDSFLT	GxASDSCLC2
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7 **GxASE:** Auto-Shutdown Event Status bit
- 1 = An auto-shutdown event has occurred
- 0 = No auto-shutdown event has occurred

bit 6 **GxARSEN:** Auto-Restart Enable bit
- 1 = Auto-restart is enabled
- 0 = Auto-restart is disabled

bit 5-2 **Unimplemented:** Read as ‘0’

bit 1 **GxASDSFLT:** CWG Auto-shutdown on FLT Enable bit
- 1 = Shutdown when $\overline{\text{CWG1FLT}}$ input is low
- 0 = $\overline{\text{CWG1FLT}}$ input has no effect on shutdown

bit 0 **GxASDSCLC2:** CWG Auto-shutdown on CLC2 Enable bit
- 1 = Shutdown when CLC2 output (LC2_out) is high
- 0 = CLC2 output has no effect on shutdown

TABLE 22-2: SUMMARY OF REGISTERS ASSOCIATED WITH CWG

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	99
CWG1CON0	G1EN	G1OEB	G1OEA	G1POLB	G1POLA	—	—	G1CS0	184
CWG1CON1	G1ASDLB<1:0>		G1ASDLA<1:0>		—	—	G1IS<1:0>		185
CWG1CON2	G1ASE	G1ARSEN	—	—	—	—	G1ASDSFLT	G1ASDSCLC2	186
CWG1DBF	—	—	CWG1DBF<5:0>						187
CWG1DBR	—	—	CWG1DBR<5:0>						187
TRISA	—	—	TRISA5	TRISA4	—(1)	TRISA2	TRISA1	TRISA0	98
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	106

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by CWG.
Note 1: Unimplemented, read as '1'.

24.2 Instruction Descriptions

ADDFSR — Add Literal to FSRn

Syntax:	[*label*] ADDFSR FSRn, k
Operands:	-32 ≤ k ≤ 31 n ∈ [0, 1]
Operation:	FSR(n) + k → FSR(n)
Status Affected:	None
Description:	The signed 6-bit literal ‘k’ is added to the contents of the FSRnH:FSRnL register pair. FSRn is limited to the range 0000h - FFFFh. Moving beyond these bounds will cause the FSR to wrap-around.

ADDLW — Add literal and W

Syntax:	[*label*] ADDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the 8-bit literal ‘k’ and the result is placed in the W register.

ADDWF — Add W and f

Syntax:	[*label*] ADDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register ‘f’. If ‘d’ is ‘0’, the result is stored in the W register. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

ADDWFC — ADD W and CARRY bit to f

Syntax:	[*label*] ADDWFC f {,d}
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) + (C) → dest
Status Affected:	C, DC, Z
Description:	Add W, the Carry flag and data memory location ‘f’. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is placed in data memory location ‘f’.

ANDLW — AND literal with W

Syntax:	[*label*] ANDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND’ed with the 8-bit literal ‘k’. The result is placed in the W register.

ANDWF — AND W with f

Syntax:	[*label*] ANDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register ‘f’. If ‘d’ is ‘0’, the result is stored in the W register. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

ASRF — Arithmetic Right Shift

Syntax:	[*label*] ASRF f {,d}
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f<7>)→ dest<7> (f<7:1>) → dest<6:0>, (f<0>) → C,
Status Affected:	C, Z
Description:	The contents of register ‘f’ are shifted one bit to the right through the Carry flag. The MSb remains unchanged. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

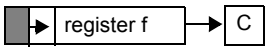


TABLE 25-5: MEMORY PROGRAMMING SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
		Program Memory Programming Specifications					
D110	V_{IHH}	Voltage on $\overline{MCLR}/V_{PP}$ pin	8.0	—	9.0	V	**(Note 2)**
D112	V_{PBE}	V_{DD} for Bulk Erase	2.7	—	V_{DDMAX}	V	
D113	V_{PEW}	V_{DD} for Write or Row Erase	V_{DDMIN}	—	V_{DDMAX}	V	
D114	I_{PPPGM}	Current on $\overline{MCLR}/V_{PP}$ during Erase/Write	—	1.0	—	mA	
D115	I_{DDPGM}	Current on V_{DD} during Erase/Write	—	5.0	—	mA	
		Program Flash Memory					
D121	E_P	Cell Endurance	10K	—	—	E/W	-40°C ≤ T_A ≤ +85°C **(Note 1)**
D122	V_{PRW}	V_{DD} for Read/Write	V_{DDMIN}	—	V_{DDMAX}	V	
D123	T_{IW}	Self-timed Write Cycle Time	—	2	2.5	ms	
D124	T_{RETD}	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
D125	E_{HEFC}	High-Endurance Flash Cell	100K	—	—	E/W	0°C ≤ T_A ≤ +60°C, lower byte last 128 addresses

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Self-write and Block Erase.

2: Required only if single-supply programming is disabled.

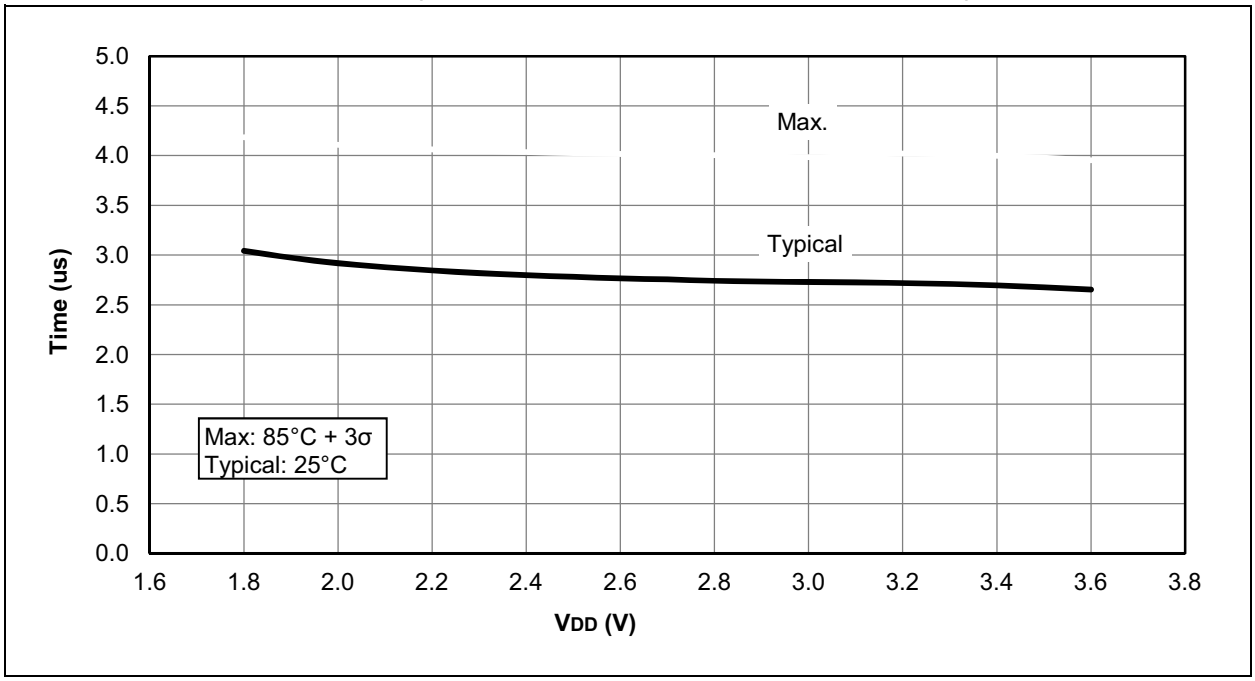
TABLE 25-6: THERMAL CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)					
Param. No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θ_{JA}	Thermal Resistance Junction to Ambient	62.2	°C/W	20-pin DIP package
			77.7	°C/W	20-pin SOIC package
			87.3	°C/W	20-pin SSOP package
			46.2	°C/W	20-pin QFN 4x4mm package
			32.8	°C/W	20-pin UQFN 4x4mm package
TH02	θ_{JC}	Thermal Resistance Junction to Case	27.5	°C/W	20-pin DIP package
			23.1	°C/W	20-pin SOIC package
			31.1	°C/W	20-pin SSOP package
			13.2	°C/W	20-pin QFN 4x4mm package
			27.4	°C/W	20-pin UQFN 4x4mm package
TH03	T_{JMAX}	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = $P_{INTERNAL}$ + $P_{I/O}$
TH05	$P_{INTERNAL}$	Internal Power Dissipation	—	W	$P_{INTERNAL}$ = I_{DD} x V_{DD} **(1)**
TH06	$P_{I/O}$	I/O Power Dissipation	—	W	$P_{I/O}$ = Σ (I_{OL} * V_{OL}) + Σ (I_{OH} * (V_{DD} - V_{OH}))
TH07	P_{DER}	Derated Power	—	W	P_{DER} = P_{DMAX} (T_J - T_A)/θ_{JA} **(2)**

Note 1: I_{DD} is current to run the chip alone without driving any load on the output pins.

2: T_A = Ambient Temperature; T_J = Junction Temperature

FIGURE 26-53: SLEEP MODE, WAKE PERIOD WITH HFINTOSC SOURCE, PIC16LF1507 ONLY



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